# 2501552-9 - ACTIVE

TE Internal #: 2501552-9 RJ45 Connector, Single Port, 1 x 1, Standard Connector Contact Density, Jack, Shielded, Cat 5, 8 Position, Standard Profile, Through Hole - Solder

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Connectors > Modular Jacks & Plugs > RJ45 Connectors > Industrial RJ45 modular jacks: 10/100 Mbps and 1 Gbps, THT reflow solderable



Modular Jack & Plug Interface Type: RJ45

Port Configuration: Single Port

Port Matrix Configuration: 1 x 1

Modular Jacks & Plugs Products: RJ Type Jacks & Plugs

Connector Contact Density: Standard

All Industrial RJ45 modular jacks: 10/100 Mbps and 1 Gbps, THT reflow solderable (36)



## Features

### Product Type Features

Connector Product Type	Connector Assembly
Modular Jack & Plug Interface Type	RJ45
Modular Jacks & Plugs Products	RJ Type Jacks & Plugs
Modular Connector Style	Jack
Grounding Options	PCB Ground
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of PCB Ground Tabs	2
Number of Panel Ground Tabs	0
Port Configuration	Single Port
Port Matrix Configuration	1 × 1
Connector Contact Density	Standard
Number of Positions	8

**C** For support call+1 800 522 6752

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Data Rate10 Mb/s, 100 Mb/sData Rate10 Mb/s, 100 Mb/sData Rate10 Mb/s, 100 Mb/sData Rate10 Mb/s, 100 Mb/sData Rate10 CPPCB Retention Feature MaterialLCPLED Color (Bottorn Left)NoneLED Color (Bottorn Kight)Reclor Yellow/GreenIssilator MaterialICPShield Plating MaterialNoneShield Plating MaterialNoneConnector ProfileCopper AlloyContact FeaturesStandardPCB Contact Termination Area Plating Material FinishMatteContact Underplating MaterialNickelContact Termination Area Plating MaterialNickelContact Curront Rating (May)1.5 AContact Mating Area Plating MaterialGoldContact Mating Area Plating MaterialPhosphor BronzeContact Mating Area Plating MaterialThrough Hole SolderTermination Method to PCBThrough Hole SolderTermination Post & Tail Length2.54 mm[1 in]Vechanical AttachmentPCB Mount Retention TypePCB Mount Retention TypeBoardlock		
Signal CharacteristicsData Rate10 Mb/s, 100 Mb/sData Rate10 Mb/s, 100 Mb/sSchor Yellow/GreenSchor Yellow/GreenEDE Color (Top Left)KorePCB Retention Feature MaterialLCPLED Color (Bottom Left)NoneLED Color (Bottom Left)NoneInsulator MaterialCOPLED Color (Bottom Left)NoneSchold MaterialCoper Allow/GreenSchold MaterialCoper AlloySchold MaterialCoper AlloyConnector ProfileSchold MaterialContext FeaturesNickelPCB Context Termination Area Plating Material FinishMatteContext Underplating MaterialNickelContext Current Rating (Mas)I.S AlloyContext MaterialColdContext Material MaterialSchold MaterialContext Material MaterialSchold ScholdContext Material Material FinishMatteContext Material MaterialSchold ScholdContext Material MaterialSchold ScholdContext Material MaterialSchold ScholdContext Material Material ThioknessSchold ScholdContext Material Material ThioknessSchold ScholdTermination Method to PCBSchold MaterialTermination Material LengthSchold MountConnector Mount TypeSchold MountC	Number of Loaded Positions	8
Paile Raile       10 Mb/s, 100 Mb/s         Babe Raile       10 Mb/s, 100 Mb/s         PCB Retention Feature Material       LCP         11D Color (Hottom Left)       None         11D Color (Rottom Right)       None         12D Contot Contect Rottom Area Pl	PCB Mount Orientation	Vertical
Body Features       Kicolor Yellow/Green         LLD Coler (Top Left)       Kicolor Yellow/Green         PCB Retention Feature Material       LCP         LED Color (Rottom Left)       None         LED Color (Top Right)       Bicolor Yellow/Green         Insulator Material       LCP         LFD Color (Rottom Right)       None         Shield Material       Copper Alloy         Connector Profile       Standard         Connector Profile       Standard         Contact Termination Area Plating Material Linish       Matte         Contact Termination Area Plating Material       Nickel         Contact Termination Area Plating Material       Sicolor Rout         Contact Termination Area Plating Material       Mickel         Contact Termination Area Plating Material       Nickel         Contact Mating Area Plating Material Linish       Matte         Contact Current Rating (Max)       1.5 A         Contact Mating Area Plating Material       Nickel         Contact Mating Area Plating Material Linish       Matte         Contact Mating Area Plating Material Linish       Sicolor Sicolor         Contact Mating Area Plating Material Linish       Sicolor Sicolor         Contact Mating Area Plating Materi	Signal Characteristics	
LD Color (Top Left)   Bicolor Yellow/Green     PCB Retention Feature Material   ICP     LD Color (Bottom Left)   None     LD Color (Top Right)   Bicolor Yellow/Green     Insulator Material   ICP     TPD Color (Rottom Right)   None     Shield Plating Material   COper Alloy     Shield Plating Material   Coper Alloy     Connector Profile   Standard     Contact Termination Area Plating Material Finish   Matte     PCB Contact Termination Area Plating Material   Nickel     Contact Underplating Material   Nickel     Contact Termination Area Plating Material   Nickel     Contact Termination Area Plating Material   Nickel     Contact Mating Area Plating Material   Sidolar Material     Contact Termination Area Plating Material   Nickel     Contact Material Maxi   Sidolar Material     Contact Mating Area Plating Material   Gold     Contact Material Material   Picsphor Bronze     Contact Material Material Thickness   Joing Sidor Material     Termination Method to PCB   Trough Hole - Solder     Termination Method to PCB   Board Material     Connector Mounting Type   Board Mount     PCB Mount Retention Type   Board Mount     Connector Mounting Type   Board Mount <td>Data Rate</td> <td>10 Mb/s, 100 Mb/s</td>	Data Rate	10 Mb/s, 100 Mb/s
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I FD Color (Top Right)Biolor Vollow/GreenI nsulator MaterialLCPLB Color (Bottom Right)NoneShield Plating MaterialCopper AlloyShield MaterialCopper AlloyConnector ProfileStandardContact FeaturesNickelPCB Contact Termination Area Plating Material FinishMatteContact Underplating MaterialNickelContact Termination Area Plating MaterialNickelContact Underplating MaterialNickelContact Termination Area Plating MaterialSoldContact Termination Area Plating MaterialGoldContact Mating Area Plating MaterialGoldContact Mating Area Plating MaterialSoldContact Mating Area Plating MaterialSoldContact Mating Area Plating MaterialSoldContact Mating Area Plating Material FinishBiosphor BronzeContact Current Rating (Max)I S AContact Mating Area Plating MaterialSoldContact Mating Area Plating MaterialSoldContact Mating Area Plating Material FinishBiosphor BronzeContact Mating Area Plating Material FinishSoldContact Mating Area Plating MaterialSoldContact Current Rating (Max)SoldContact Mating Area Plating MaterialSoldContact Mating Area Plating Material FinishBiosphor BronzeContact Mating Area Plating Material FinishSoldContact Mating Area Plating MaterialSoldContact Mating Area Plating Material FinishBiosphor BronzeContac	PCB Retention Feature Material	LCP
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LED Color (Bottom Right)     None       Shield Plating Material     Nickel       Shield Material     Copper Alloy       Connector Profile     Standard       Contact Features     Vickel       PCB Contact Termination Area Plating Material Finish     Matte       Contact Ouderplating Material     Nickel       Contact Current Rating (Max)     In       Contact Current Rating (Max)     Sold       Contact Mating Area Plating Material     Gold       Contact Mating Area Plating Material     Gold       Contact Mating Area Plating Material     Sold       Contact Mating Area Plating Material     Foresponsore       Contact Mating Area Plating Material     Foresponsore       Contact Mating Area Plating Material Thickness     Job planparote       Termination Method to PCB     Through Hole Solder       Termination Post & Tail Length     Sold Material       Vectorical Attachment     Sold Material       PCB Mount Retention Type     Board Mounting       Connector Mounting Type     Sold Mounting       Hating Entry Location     Top       Mating Color     Sold Mounting	LED Color (Top Right)	Bicolor Yellow/Green
Shield Plating MaterialNickelShield MaterialCopper AlloyConnector ProfileStandardContact FeaturesVickelPCB Contact Termination Area Plating Material FinishMatteContact Underplating MaterialNickelPCB Contact Termination Area Plating MaterialTinContact Current Rating (Max)1.5 AContact Mating Area Plating MaterialGoldContact Mating Area Plating MaterialGoldContact Mating Area Plating MaterialJospor BronzeContact Mating Area Plating Material ThicknessJospor BronzeTermination Post & Tail LengthJospor BronzeVechanical AttachmentSoard MountPCB Mount Retention TypeBoard MountHousing FeaturesVickelMating Finty LocationTopMating ColorBoard MountSing ColorBoard MountSing ColorSoard MountS	Insulator Material	LCP
Shield MaterialCopper AlloyConnector ProfileStandardContact FeaturesVerticePCB Contact Termination Area Plating Material FinishMatteContact Underplating MaterialNickelContact Current Rating (Max)1.5 AContact Current Rating (Max)GoldContact Mating Area Plating MaterialGoldContact Mating Area Plating MaterialGoldContact Mating Area Plating Material76 µm(30 µin]Contact Mating Area Plating Material Thickness76 µm(30 µin]Contact Mating Area Plating Material ThicknessSid µm(1 µin]Contact Material ThicknessSid µm(1 µin]Connector Mounting TypeBoard MountConnector Mounting TypeBoard MountConnector Mounting TypeTopMating Entry LocationTopMating ColorBick	LED Color (Bottom Right)	None
Connector Profile     Standard       Connector Profile     Standard       Contact Features     Natte       PCB Contact Termination Area Plating Material Finish     Matte       Contact Underplating Material     Nickel       PCB Contact Termination Area Plating Material     Tin       Contact Current Rating (Max)     1.5 A       Contact Mating Area Plating Material     Gold       Contact Mating Area Plating Material     Phosphor Bronze       Contact Mating Area Plating Material Thickness     .6 µm(30 µin)       Contact Mating Area Plating Material Thickness     .6 µm(30 µin)       Termination Method to PCB     Through Hole - Solder       Termination Post & Tail Length     2.54 mm(1 in)       Vectanical Attachment     PCB Mount Retention Type       PCB Mount Retention Type     Board Mount       Pcompetities     Sold Mount       Housing Features     Top	Shield Plating Material	Nickel
Contact Features       PCB Contact Termination Area Plating Material Finish     Matte       Contact Underplating Material     Nickel       PCB Contact Termination Area Plating Material     Tin       PCB Contact Termination Area Plating Material     Gold       Contact Current Rating (Max)     Gold       Contact Atting Area Plating Material     Gold       Contact Base Material     Phosphor Bronze       Contact Mating Area Plating Material Thickness     Jo pm(30 µin)       Contact Mating Area Plating Material Thickness     Jo pm(30 µin)       Contact Mating Area Plating Material Thickness     Jo pm(30 µin)       Contact Mating Area Plating Material Thickness     Jo pm(30 µin)       Contact Mating Area Plating Material Thickness     Jo pm(30 µin)       Contact Mating Area Plating Material Thickness     Jo pm(30 µin)       Contact Mating Area Plating Material Thickness     Jo pm(30 µin)       Contact Mating Area Plating Material Thickness     Jo pm(30 µin)       Premination Post & Tail Length     Jo pm(30 µin)       Post Mount Retention Type     Boardlock       Connector Mounting Type     Board Mount       Post Mount Retention Type     Top       Mating Entry Location     Top       Mating Entry	Shield Material	Copper Alloy
PCB Contact Termination Area Plating Material FinishMattePCB Contact Underplating MaterialNickelPCB Contact Termination Area Plating MaterialTinContact Current Rating (Max)1.5 AContact Mating Area Plating MaterialGoldContact Mating Area Plating MaterialGoldContact Mating Area Plating Material Thickness.76 µm(30 µin)Contact Mating Area Plating Material Thickness.76 µm(30 µin)Termination Method to PCBMaterial ThicknessTermination Post & Tail Length.76 µm(30 µin)Vechanical Attachment.70PCB Mount Retention Type.70Connector Mounting Type.70Mating Entry Location.70Mating Entry Location.70Housing Color.70Mating Entry Location.70Mating Entry Location<	Connector Profile	Standard
Contact Underplating MaterialNickelPCB Contact Termination Area Plating MaterialTinContact Current Rating (Max)1.5 AContact Mating Area Plating MaterialGoldContact Base MaterialGoldContact Base MaterialArea Plating MaterialContact Mating Area Plating MaterialArea Plating MaterialContact Base MaterialPhosphor BronzeContact Mating Area Plating Material Thickness.76 µm[30 µin]Termination FeaturesThrough Hole - SolderTermination Method to PCBThrough Hole - SolderTermination Post & Tail LengthLosing Hole - SolderPCB Mount Retention TypeBoardlockPCB Mount Retention TypeBoardlockHoting Entry LocationTopHuting Entry LocationTopHuting ChorBlack	Contact Features	
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Contact Mating Area Plating MaterialGoldContact Base MaterialPhosphor BronzeContact Mating Area Plating Material Thickness.76 µm[30 µin]Contact Mating Area Plating Material Thickness.76 µm[30 µin]Fermination FeaturesThrough Hole - SolderTermination Method to PCBThrough Hole - SolderTermination Post & Tail Length2.54 mm[.1 in]PCB Mount Retention TypeBoardlockConnector Mounting TypeBoard MountHousing FeaturesTopMating Entry LocationTopHousing ColorBlack	PCB Contact Termination Area Plating Material	Tin
Contact Base MaterialPhosphor BronzeContact Mating Area Plating Material Thickness.76 μm[30 μin]Fermination FeaturesThrough Hole - SolderTermination Method to PCBThrough Hole - SolderTermination Post & Tail Length2.54 mm[.1 in]PCB Mount Retention TypeBoardlockConnector Mounting TypeBoard MountHusing Entry LocationTopHousing ColorBlack	Contact Current Rating (Max)	1.5 A
Contact Mating Area Plating Material Thickness	Contact Mating Area Plating Material	Gold
Termination Features     Through Hole - Solder       Termination Method to PCB     Through Hole - Solder       Termination Post & Tail Length     2.54 mm[.1 in]       Vechanical Attachment     Vechanical Attachment       PCB Mount Retention Type     Boardlock       Connector Mounting Type     Board Mount       Housing Features     Top       Mating Entry Location     Black	Contact Base Material	Phosphor Bronze
Termination Method to PCBThrough Hole - SolderTermination Post & Tail Length2.54 mm[.1 in]Vechanical AttachmentBoardlockPCB Mount Retention TypeBoardlockConnector Mounting TypeBoard MountHousing FeaturesTopMating Entry LocationTopHousing ColorBlack	Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
Termination Post & Tail Length     2.54 mm[.1 in]       Mechanical Attachment     Soardlock       PCB Mount Retention Type     Boardlock       Connector Mounting Type     Board Mount       Housing Features     Top       Housing Color     Black	Termination Features	
PCB Mount Retention Type     Boardlock       Connector Mounting Type     Board Mount       Housing Features     Top       Housing Color     Black	Termination Method to PCB	Through Hole - Solder
PCB Mount Retention TypeBoardlockConnector Mounting TypeBoard MountHousing FeaturesTopMating Entry LocationTopHousing ColorBlack	Termination Post & Tail Length	2.54 mm[.1 in]
Connector Mounting Type     Board Mount       Housing Features     Top       Mating Entry Location     Top       Housing Color     Black	Mechanical Attachment	
Housing Features     Mating Entry Location     Housing Color	PCB Mount Retention Type	Boardlock
Mating Entry LocationTopHousing ColorBlack	Connector Mounting Type	Board Mount
Housing Color Black	Housing Features	
	Mating Entry Location	Тор
Housing Material LCP (Liquid Crystal Polymer)	Housing Color	Black
	Housing Material	LCP (Liquid Crystal Polymer)

### 2501552-9

RJ45 Connector, Single Port, 1 x 1, Standard Connector Contact Density, Jack, Shielded, Cat 5, 8 Position, Standard Profile, Through Hole - Solder



### Dimensions

Connector Height	15.75 mm[.62 in]	
Usage Conditions		
Operating Temperature Range	-40 – 85 °C[-40 – 185 °F]	
Operation/Application		
Indicator Type	LED	
Shielded	Yes	
Industry Standards		
UL Flammability Rating	UL 94V-0	
Performance Category	Cat 5	
Packaging Features		
Packaging Method	Tray	
Product Compliance For compliance documentation, visit the product page on TE.com>		

EU RoHS Directive 2011/65/EUCompliantEU ELV Directive 2000/53/ECNot Yet Reviewed

China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not reviewed for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked.Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the

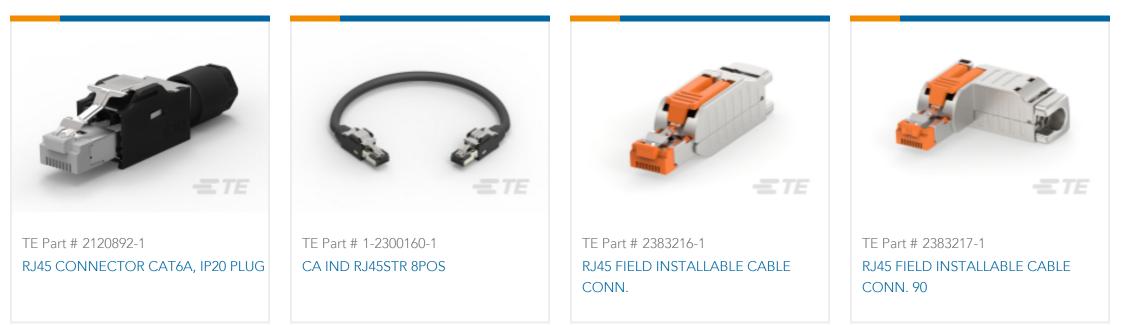
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product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

# **Compatible Parts**



## Documents

### Product Drawings RJ45 JACK THR 10/100 VERT. LED 1X1

English

### **CAD** Files

3D PDF

3D

Customer View Model ENG\_CVM\_CVM\_2501552-9\_1.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_2501552-9\_1.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2501552-9\_1.3d\_stp.zip

English

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Product Specifications Application Specification

English